





July 27, 2000

N THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Applica	ition of:)
TAKAYAMA et al.)
Serial No.:	09/598,736) hereby certify that this correspondence is being deposited with the United States Postal Service as
Filed:	June 21, 2000	the Assistant Commissioner for Patents, Washington, D.C. 20231 on 1414 27, 2000
For: Wiring Material, Semiconductor Device Provided With A Wiring Using The Wiring Material And Method Of Manufacturing Thereof		(Date of Deposit) (Name of applicant, assignee, or Registered Rep. (Date of Deposit) (Date of Deposit) (Date of Deposit) (Date of Deposit)
Examiner:		
Art Unit:)

Assistant Commissioner for Patents Washington D.C. 20231

PRELIMINARY AMENDMENT A

Prior to examination, please enter the following amendment in the above-identified application:

IN THE DRAWINGS:

Please amend the enclosed drawings as shown in red.

REMARKS

This amendment is being submitted to correct the drawings as filed.

In particular, in Fig. 30 as filed, the graph had a typographical error that showed "resistivity" v. sputtering power. The label "resistivity" was erroneous put on the graph. It should have been "stress". This is supported by the specification. For example, page 8, lns. 10-11 state "Fig. 30 is a graph showing the relationship between sputtering power and stress" (emphasis added). See also